Meng-Hsin Chen
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Task-oriented engineer, leveraging robust problem-solving skills and 8 years of Process Integration experience in TSMC, equipped with the most advanced knowledge of the semiconductor and packaging industry. To expand the horizon, pursued self-study in programming and IT. Started a new path as a Customer Technical Support Engineer at Microsoft propelled by the choice, specializing in the realm of process automation and low-code applications, assisting global enterprise customers, and playing a role in enhancing Microsoft products by delivering valuable customer feedback. Possess a natural ability to quickly grasp new concepts and adapt to unfamiliar fields, embracing a growth mindset, with passion for continuous self-improvement.

Expertise

Languages	English - Full professional proficiency (TOEFL iBT: 112); Mandarin Chinese - Native
Programming	C#, JavaScript/HTML/CSS, VBA
IT	RDBMS/SQL, UI Design, Azure, Microsoft Power Platform/Apps/Automate/Virtual Agents
Industry Knowledge	Advanced Packaging, Process Integration, Yield Improvement, Technology Management
Certificates	Microsoft Certified AZ-900: Azure Fundamentals
	Microsoft Certified PL-900: Power Platform Fundamentals

Experience

Microsoft
- **Customer Technical Support Engineer**, Taipei (Jul 2022 - present)
  - Integrated customers need to implement and arrange Microsoft cloud product improvement plans, including Azure cloud services, Dynamics CRM, and Power Platform low-code applications.
  - Cooperated with APAC region enterprise users and provided technical guidance and system training.
  - Assisted over 300 organizations to build project solutions and resolve technical issues with highly-skilled and customer-focused professionals.

TSMC
- **System Integration Engineer**, Taoyuan (Apr 2020 - Jul 2022)
  - Used SQL(Oracle) and API to develop web applications for data analysis based on ASP.NET framework.
  - Developed Windows programs using C#, VBA, and SQL for productivity enhancement.
  - Communicated with users to define requirements, design/deploy/implement/test system for continuous improvements.
  - Supervised a team of 5 technicians to handle customer requests for new product design to meet special demands.
- **Technology Core Team Engineer**, Hsinchu (Feb 2019 - Apr 2020)
  - Defined the 1st process flow auto-creation SOP for TSMC 3DFabric.
  - Defined bumping/assembly technology infrastructure for 3D IC roadmap. (Division Stop & Fix Award Winner)
  - Handled process change with perfect quality management, considering interactions between technologies and processes.
- **Advanced Packaging Process Integration Engineer**, Taoyuan (Nov 2014 - Feb 2019)
  - Developed InFO along with SoC throughout N16/N10/N7/N5 technology. (Suggestion Committee Award Winner)
  - Saved expense cost by constructing preserving methodologies of goods. (Division Contribution Award)
  - Collaborated with customers on inline issue resolution and yield improvement.

Education

Linköping University (Linköping, Sweden)
- **Exchange Program**, Institute of Technology (2013 - 2014)

National Taiwan University (Taipei)
- **Master**, Science in Materials Science and Engineering (2011 - 2013)
  - Thesis: Interfacial Reactions Between Copper Substrate and Lead-Free Solder for 3D IC Applications
  - Session Presenter, TMS 2012 Annual Meeting & Exhibition (Orlando, FL)
  - Poster, Material Research Society-Taiwan (MRS-T) (Yunlin)
- **Bachelor**, Science in Materials Science and Engineering (2007 - 2011)
  - Presidential Award Winner
  - Visiting Student, University of Oxford (Oxford, UK)